

Abstracts

Characterization of surface mount packages at microwave frequencies using wafer probes

E.M. Godshalk. "Characterization of surface mount packages at microwave frequencies using wafer probes." 2000 MTT-S International Microwave Symposium Digest 00.3 (2000 Vol. III [MWSYM]): 1887-1890.

Calibrated measurements are performed in a printed circuit board (PCB) environment using microstrip elements and ultra-small surface mount components as calibration standards. The calibration technique allows surface mount packages to be characterized from VHF to microwave frequencies. The use of microwave wafer probes for connection to the PCB is described.

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